EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"4497875".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:28
L2	189049	(first second third plural$4 multiple) with (copper cu laminat$4) with (plat $3 metal layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:44
L3	397668	(first second third plural$4 multiple) with (copper cu metal $3 laminat$4) with (plat$3 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:44
L4	8721195	(semiconductor die chip element ic (integrated adj circuit) ic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:45
L5	399858	(first second third plural$4 multiple) with (copper cu metal $3 laminat$4 laminar) with (plat$3 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:45
L6	134649	4 same 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:46
L7	90325	4 with 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:47
L8	1703	(heat with (sink spreader radiat$4)) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:54
L9	117459	thermal with stress	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:55

L10	94706	(copper cu) with carbon$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:55
L11	193	9 same 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:56
L12	193	10 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:56
L13	304	8 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:56
L14	340	8 and (9 10)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 07:57
L15	4	"2002043482"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 08:09

6/6/08 8:20:15 AM
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